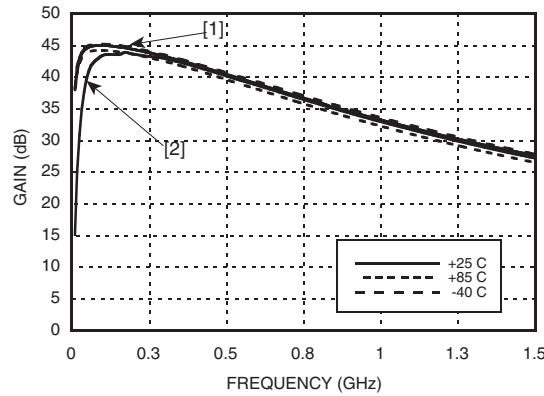


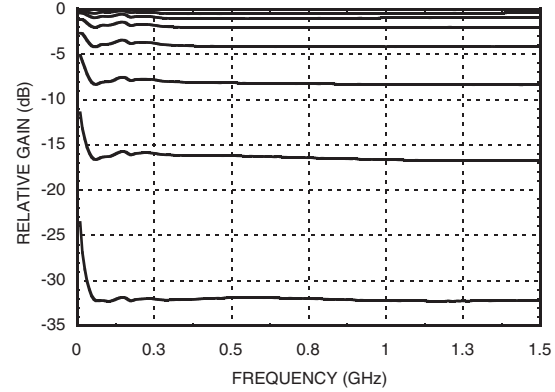
## 0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, DC - 1 GHz

**Gain vs. Frequency<sup>[1]</sup>**



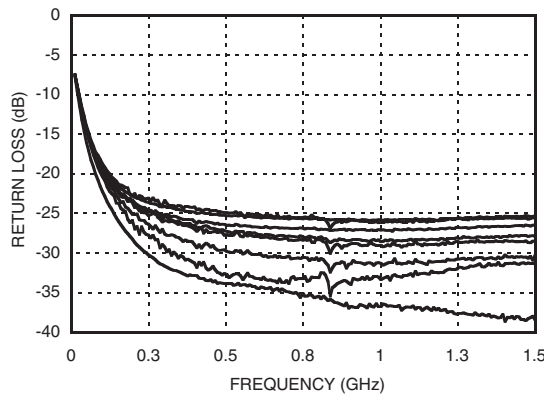
**Relative Gain Setting**

(Referenced to Maximum Gain State)  
(Only Major States are Shown)



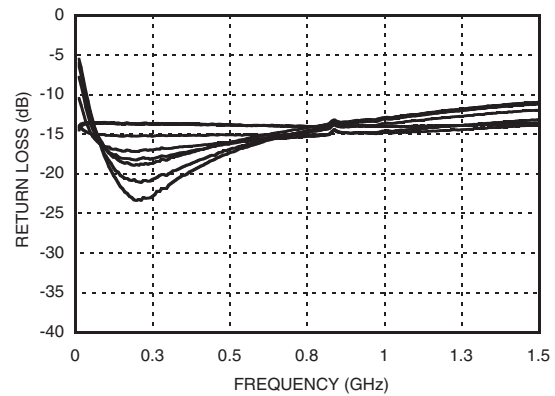
**Input Return Loss<sup>[1]</sup>**

(Only Major States are Shown)



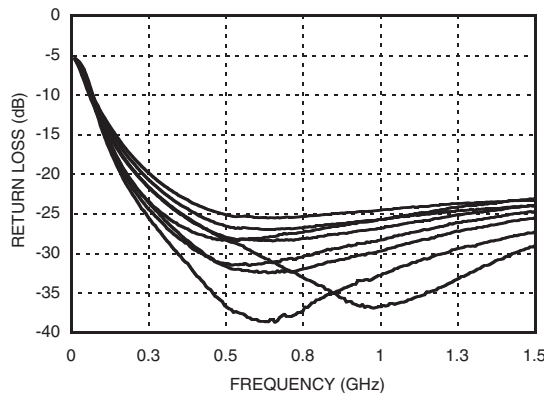
**Output Return Loss<sup>[1]</sup>**

(Only Major States are Shown)



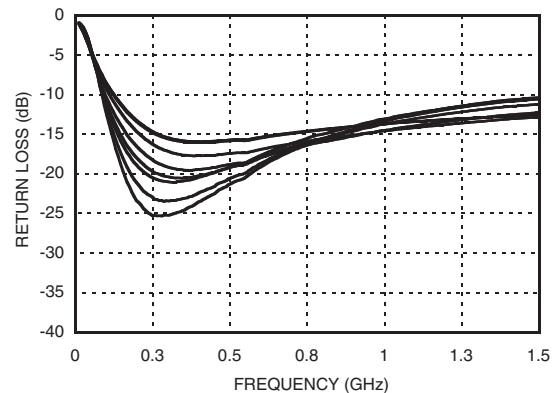
**Input Return Loss<sup>[2]</sup>**

(Only Major States are Shown)



**Output Return Loss<sup>[2]</sup>**

(Only Major States are Shown)



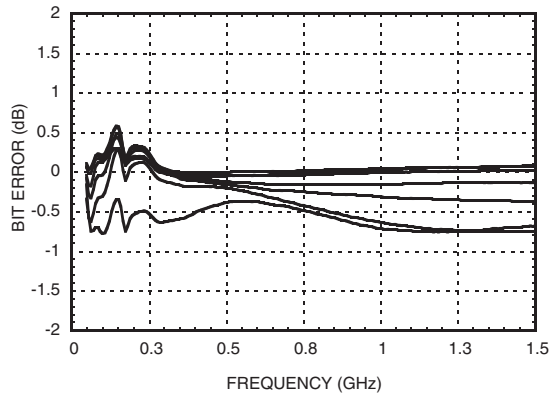
[1] Tested with broadband bias tee on output J2, C7, C8 = 10,000pF ; L1 = 680nH

[2] Data taken on eval board as described in data sheet

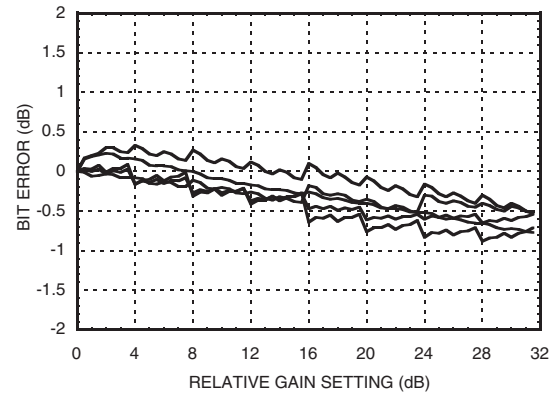
## 0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, DC - 1 GHz

### Bit Error vs. Frequency<sup>[2]</sup>

(Only Major States are Shown)

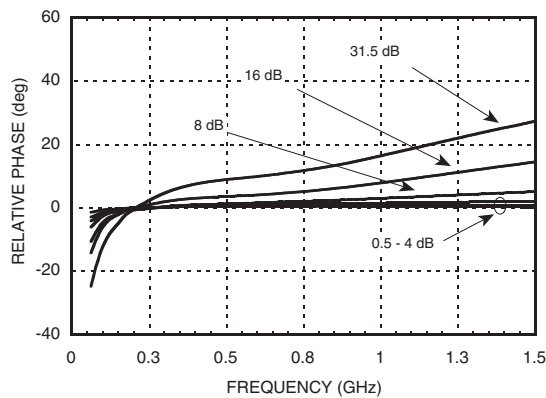


### Bit Error vs. Relative Gain Setting<sup>[2]</sup>



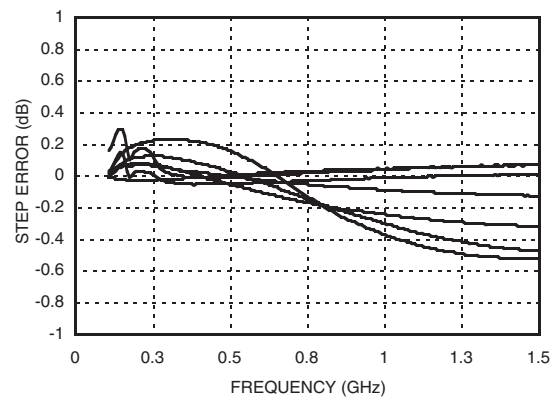
### Relative Phase vs. Frequency<sup>[2]</sup>

(Only Major States are Shown)



### Step Error vs. Frequency<sup>[2]</sup>

(Only Major States are Shown)



[1] Tested with broadband bias tee on output J2, C7, C8 = 10,000pF ; L1 = 680nH

[2] Data taken on eval board as described in data sheet

## 0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, DC - 1 GHz

### Bias Voltage & Current

Vdd (V)	Idd (Typ.) (mA)
+4.5	4.7
+5.0	5.0
+5.5	5.3
Vs (V)	Is (mA)
+5.0	176

### Control Voltage Table

State	Vdd = +3V	Vdd = +5V
Low	0 to 0.5V @ <1 $\mu$ A	0 to 0.8V @ <1 $\mu$ A
High	2 to 3V @ <1 $\mu$ A	2 to 5V @ <1 $\mu$ A

### Truth Table

Control Voltage Input						Relative Gain Setting
V1 16 dB	V2 8dB	V3 4 dB	V4 2 dB	V5 1 dB	V6 0.5 dB	
High	High	High	High	High	High	Reference 0 dB
High	High	High	High	High	Low	-0.5 dB
High	High	High	High	Low	High	-1 dB
High	High	High	Low	High	High	-2 dB
High	High	Low	High	High	High	-4 dB
High	Low	High	High	High	High	-8 dB
Low	High	High	High	High	High	-16 dB
Low	Low	Low	Low	Low	Low	-31.5 dB

Any combination of the above states will provide a relative gain setting approximately equal to the sum of the bits selected.



## 0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, DC - 1 GHz

### Absolute Maximum Ratings

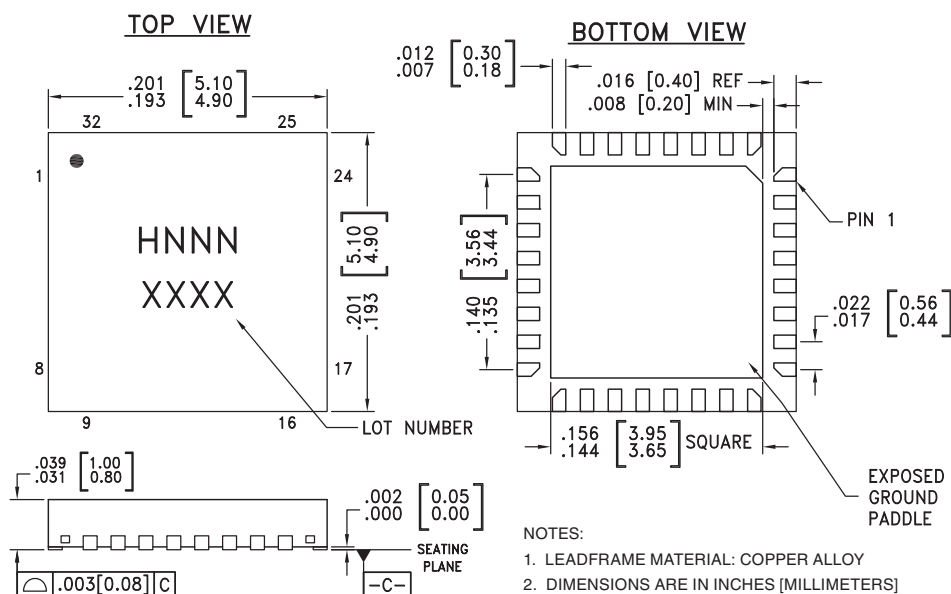
RF Input Power <sup>[1]</sup> (At Max Gain Setting)	-10.5 dBm (T = +85 °C)
Bias Voltage (Vdd)	+5.5 Vdc
Collector Bias Voltage (Vcc)	5.5 Vdc
Channel/Junction Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 19.8 mW/°C above 85 °C) <sup>[1]</sup>	1.29 W
Thermal Resistance	50.8 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

[1] The Max RF Input Power Rating will increase by 0.5 dB for every 0.5 dB reduction in gain to a maximum RF Input Power of 10 dBm.

## Outline Drawing



## Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking <sup>[3]</sup>
HMC626LP5	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 <sup>[1]</sup>	H626 XXXX
HMC626LP5E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 <sup>[2]</sup>	<u>H626</u> XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

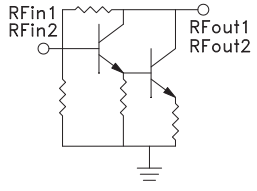

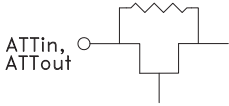
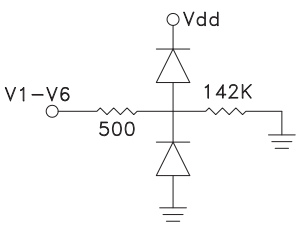
[3] 4-Digit lot number XXXX

NOTES:

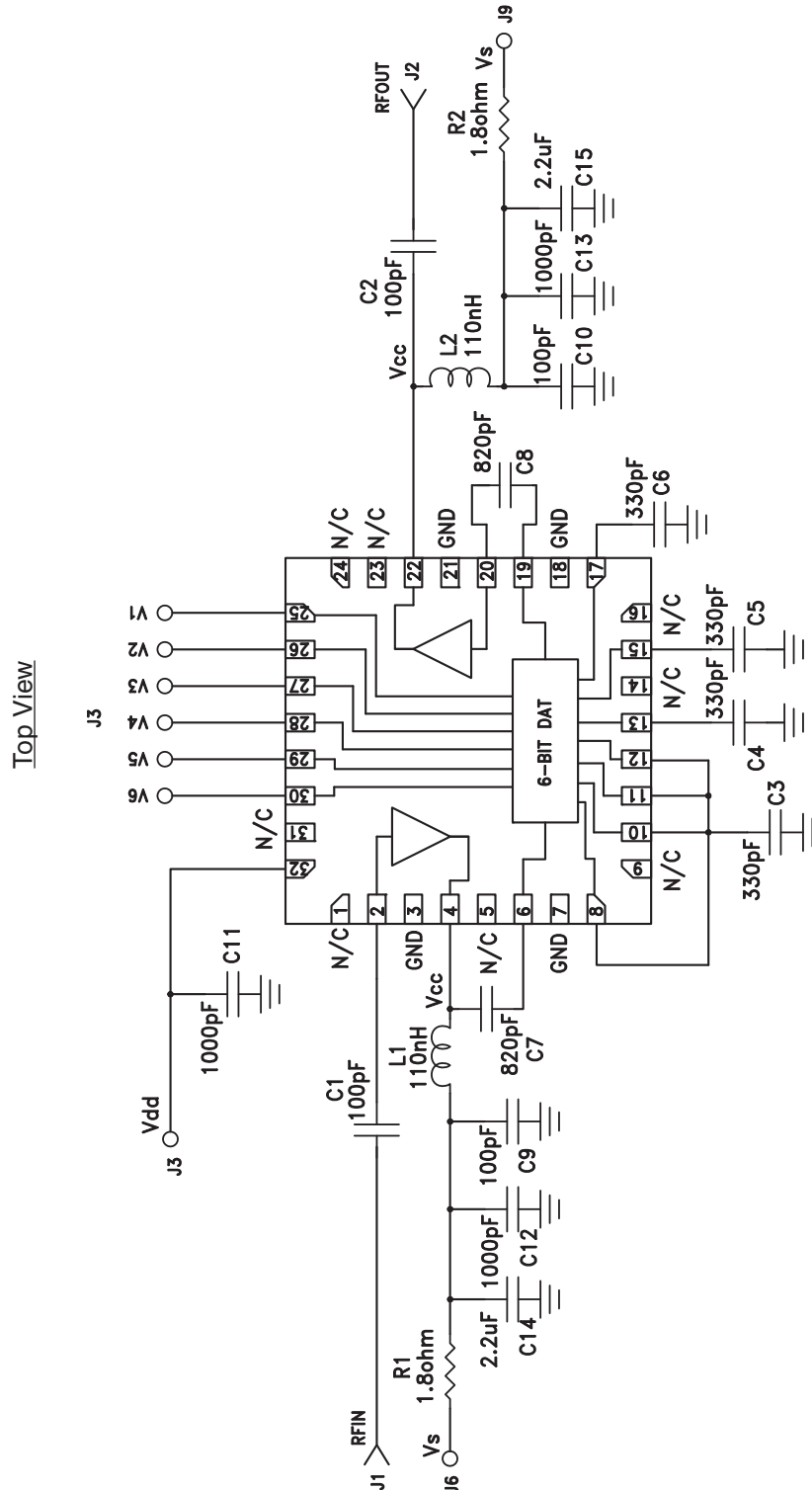
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.  
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE  
SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED  
LAND PATTERN.

## 0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, DC - 1 GHz

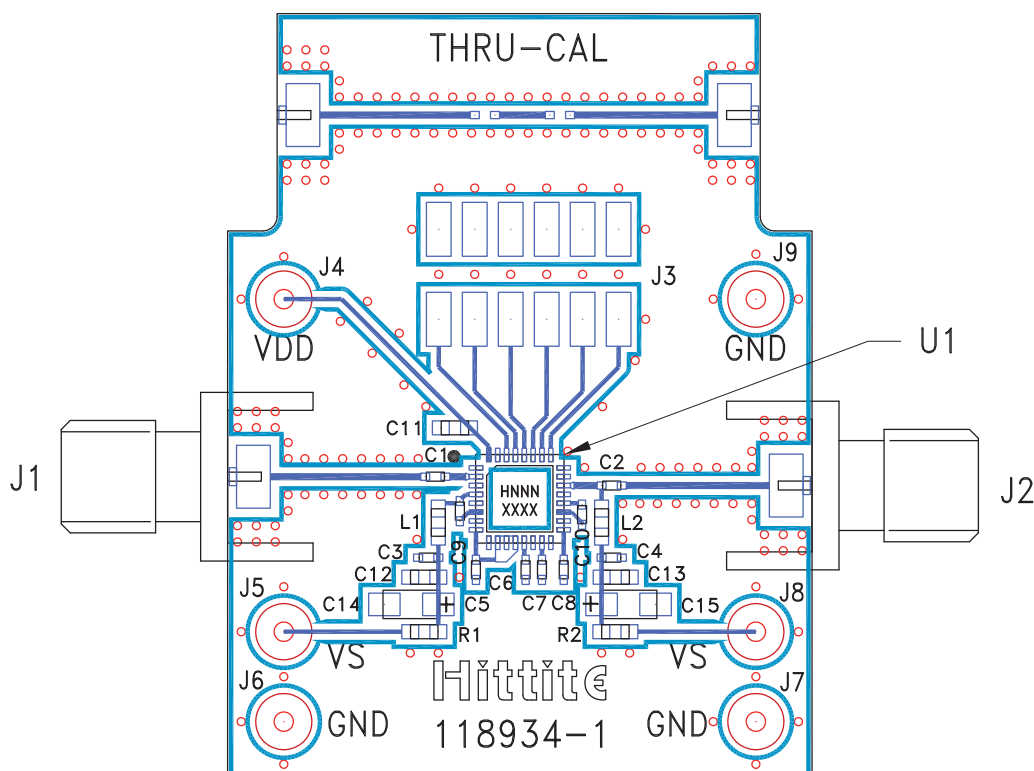
### Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 5, 9, 14, 16, 23, 24, 31	N/C	These pins may be connected to RF/DC ground. Performance will not be affected.	
2, 20	RFin1, RFin2	This pin is DC coupled. An off chip DC blocking capacitor is required.	
4, 22	RFout1, RFout2	RF output and DC bias (Vcc) for the output stage of the amplifiers. Amplifier bias provided via external bias tee as shown in application circuit.	
3, 7, 18, 21	GND	These pins and package bottom must be connected to RF/DC ground.	
6, 19	ATTin, ATTout	These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required. Select value based on lowest frequency of operation.	
8, 10, 11, 12, 13, 15, 17	ACG1, ACG2, ACG3, ACG4, ACG5, ACG6, ACG7	External capacitors to ground is required. Select value for lowest frequency of operation. Place capacitor as close to pins as possible.	
25 - 30	V1 - V6	See truth table, control voltage table and timing diagram.	
32	Vdd	Supply voltage	

**Application Circuit**



### Evaluation PCB



### List of Materials for Evaluation PCB 117355 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	12 Pin DC Connector
J4 - J9	DC Pin
C1, C2, C9, C10	820 pF Capacitor, 0402 Pkg.
C3, C4	100 pF Capacitor, 0402 Pkg.
C5 - C8	330 pF Capacitor, 0402 Pkg.
C11 - C13	1000 pF Capacitor, 0402 Pkg.
C14, C15	2.2 $\mu$ F Capacitor, CASE A Pkg.
R1, R2	1.8 Ohm Resistor, 0603 Pkg.
L1, L2	110 nH Inductor, 0603 Pkg.
U1	HMC626LP5(E) Variable Gain Amplifier
PCB [2]	118934 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.